

CEQM67HD Type 6 95x125mm COM, 2nd Gen Intel Core i7

Type 6, 95x125mm COM, 2nd Gen Intel Core i7, -40 to +85C

The CEQM67HD provides extreme ruggedness and -40°C to +85°C temperature range combined with the second generation quad-core Intel Core i7 processor and the Mobile Intel QM67 Express chipset to provide breakthrough processing performance on a basic size Type 6 COM Express Revision 2.0 module.

The basic size 95mm x 125mm module is ideal for compute intensive applications such as defense and aerospace communications, processing, test and control that require high levels of processing performance.

Radisys delivers the CEQM67HD module in a COM Express Revision 2.0, Type 6 pin out, enabling customers to take advantage of new technology such as Digital Display Ports while boosting features and performance with up to 16GB memory, additional PCI Express lanes, and improved storage, graphics and audio. The CEQM67HD module provides (Trusted Platform Module) TPM support as well as support for Intel Advanced Management Technology (AMT) enabling remote access and diagnostics via the Radisys Embedded Software Platform (eSP).

The Radisys COM Express (CE) family of products enables customers to start designing at the same time as processor release, saving months of development time and resources. OEM focus can remain on core competencies such as software and application development rather than high speed circuit design. Planned feature changes, demand fluctuations and performance upgrades can be handled without product redesigns using the CE family. CE modules can reduce service repair inventories, and simplify upgrades, contributing to the success of the product over its lifetime.



PROCESSOR VARIANTS

Module Specs	Description	Compare Modules
CEQM67HD-2655-0	Intel Core i7 2655LE / 2.2GHz / 2 Core / 4MB Cache	Add to Comparison



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COM EXPERT DESIGN SERVICES

OEMs can depend on the Radisys COM Expert team to support their design at every stage, from schematic checks to the handling of entire custom carrier and system designs.

Radisys COM Expert services include options for software utilities, custom BIOS, mechanical models, debug assistance and more to customers using Radisys CE processor modules. Design consulting and debug services are also available to support OEM product development at any stage. Ask your Radisys Account Executive for more information.

FEATURES

- -40°C to +85°C operating temperature
- Intel Core i7 Processor options
 - Intel Core i7 2655LE, 2.2GHz
- Mobile Intel QM67 Express chipset
- Dual-channel DDR3, up to 16GB
- Type 6 COM Express Revision 2.0
- Basic 95mm x 125mm size
- Seven PCI Express x1 ports (may be used in x4, x2 configurations)
- One PCI Express x16 PEG port (may be used in x8, x4 configurations)
- Three Digital Display Interfaces (DDI)
- Single Gigabit Ethernet
- TPM and AMT support
- One serial port

SPECIFICATIONS

Feature	Function	Description
Pin-Out	Type	Type 6, 95mm x 125mm
	Compliance	PICMG COM Express R2.0 Basic Form Factor
Processor	2655LE	Core i7 2655LE 2.2GHz / 4MB cache / 25W
Chipset	Mobile Intel QM67 Express chipset	
Memory	Type	Two 204-pin right-angle SO-DIMM sockets, 1333MT/s and 1067MT/s
	Capacity	Up to 8GB per channel, for a maximum of 16GB memory
Flash	8MB system flash for BIOS storage	
Video	Intel Gen 6.0 integrated graphics engine	LVDS supports 18 bit or 24 bit panel, single- or dual-channel, supports resolutions up to 1920×1200 pixels at 60 Hz
		VGA
		Up to 3 Digital Display Interfaces <ul style="list-style-type: none"> • DDI 1 (PCH Port B) supports DisplayPort, HDMI or SDVO • DDI 2 (PCH Port C) supports DisplayPort or HDMI • DDI 3 (PCH Port C) supports DisplayPort, HDMI or eDP
	External	One x16 PCI Express interface for external PCIe x16 graphics device,
Networking	Single Lan	One 10/100/1000BaseT
Audio	High Definition Audio	
	Speaker Out	

Storage	SATA	4 SATA ports supporting 1.5 and 3.0 Gbps operation, Ports 0 and 1 support 6Gbps (SATA3) Supports RAID 0, 1, 5 and 10
PCI Express	PCI Express x1	Seven PCI Express x1 Ports: <ul style="list-style-type: none"> • Ports 0–3 configurable as one x4, or two x2; or one x2 and two x1; or four x1 ports. • Ports 4-6 can be configured as three x1 or one x2 and one x1 ports
	PCI Express x16	One PCI Express x16 Graphics Expansion Port <ul style="list-style-type: none"> • Configurable as two x8 or one x8 and two x4 ports
USB	Eight USB 2.0 expansion ports	
LPC	One LPC interface	
TPM	ATMEL AT97SC3204	
Power	+12 power rail, primary input Supports 9.0V–16.8V power supply	
Power Management	ACPI 4.0 supporting states 50, 53, 54, 55 63 and C0, C1, C3, C6, C7 AMT support Intel ME Power States M0, M3, Mox	
Miscellaneous	One 100KHz SMBus from PCH	
	One 400KHz I ² C bus from MCU	
	Eight GPIO (four GPI and four GPO)	
	Watchdog timer	
	Serial port	
BIOS	AMI EFI Firmware	
OS	Windows XP	Embedded Professional 32bit Professional 64bit
	Windows Embedded Standard 7	32bit 64bit
	Red Hat Enterprise Linux 6.0	32bit 64bit
	Fedora Linux 15.0	32bit and 64bit

Physical Specifications

Physical	Dimensions	95mm x 125mm	
	Compliance	PICMG COM Express R2.0 Basic Form Factor, Type 6	
Environment	Temperature	Operating	Up to 2300m (7500 ft), -40°C to +85°C Derated -1.1 C per 305 m (1000 ft) above 2300 m (7500 ft)

	Non-operating	-40°C to +85°C
Shock	Operating	40G, half sine shock pulse, 11ms duration, 3 times per face
	Non-Operating/Unpacked	50G, half sine shock pulse, 11ms duration, 3 times per face (unpackaged)
	Transportation/Packaged	Drop test, 10-up bulk packaging, 30in free-fall, one drop on each of six faces
Vibration (random)	Operating	Random 5Hz to 2KHz, 12.07 grms, 1hour in each of 3 axes 5Hz – 40Hz: 0.04g ² /Hz 40Hz to 100Hz: 0.04g ² /Hz ramping up to 0.1g ² /Hz (3dB/Oct) 100Hz to 1000Hz: 0.1g ² /Hz 1000Hz to 2000Hz: 0.1g ² /Hz ramping down to 0.025g ² /Hz (6dB/Oct)
	Non-Operating/Storage	Random 5Hz to 2KHz, 12.07 grms, 1hr in in each of 3 axes 5Hz – 40Hz: 0.04g ² /Hz 40Hz – 100Hz: 0.04g ² /Hz ramping up to 0.1g ² /Hz (3dB/oct) 100Hz to 1000Hz: 0.1g ² /Hz 1000Hz to 2000Hz: 0.1g ² /Hz ramping down to 0.025g ² /Hz (6dB/oct) 5-500 Hz swept sine, 2.5 g (0-p), 25.4mm(p-p) MAX displacement, 5 min dwell at 3 resonances in each of 3 axes.
Humidity	Operating	5% to 95% non-condensing. 95%RH@30C, linear derating to 25%RH@85C
	Non-Operating/Storage	5% to 95% non-condensing
Altitude	Operating	To 15,000ft (4570m)
	Non-Operating/Storage	To 40,000ft (12000m)
Regulatory	Safety	UL60950-1, EN60950-1, IEC60950-1 RoHS compliant
	EMC	EN55024, EN55022, and FCC Part 15, Subpart B, Class B
Warranty	Standard	Two years, parts only

MORE DETAILS

Order Codes:

- CEQM67HD-2655-0: Corei7-2655LE, 2.2GHz, 2 Core, 4M Cache, HDG3000, TPM, -40c to 85c

Supporting Products:

- CE-4GB-DDR3IT: 2GB DDR3 SODIMM Memory, -40C to +80C
- CE-8GB-DDR3IT: 8GB DDR3 SODIMM Memory, -40C to +80C
- CEQM67-AHS: Active Heat Sink

- CEQM67-77-HSP: Heatspreader
- CEQM67-77-PHSA: Passive Heat Sink
- CR300-1: Type 6 COM Express Development Carrier

SUPPORT DOWNLOADS

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